

**RECEIVED**  
**CENTRAL FAX CENTER**  
**AUG 19 2009**

Application Serial No: 10/564,114  
Responsive to the final Office Action mailed on: May 22, 2009

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A module comprising:  
a substrate; and  
a plurality of semiconductor packages, each comprising a semiconductor chip,  
mounted on the substrate;  
wherein each of the plurality of semiconductor packages comprises a first radio  
communication element that is constituted independently of the semiconductor chip so as  
to transmit and receive a signal between the semiconductor chips in the plurality of  
semiconductor packages by radio communication, ~~and~~  
the first radio communication element comprises an antenna and an RF  
circuit[[]], and  
a surface of the first radio communication element in each of the plurality of  
semiconductor packages includes a first portion provided with a shielding layer and a  
second portion provided with no shielding layer, and an electromagnetic wave is input  
and output only through the second portion to transmit and receive a signal.
2. (Original) The module according to claim 1, wherein each of the plurality of  
semiconductor packages further comprises a resin portion for sealing the semiconductor  
chip.
3. (Original) The module according to claim 1, wherein each of the plurality of  
semiconductor packages further comprises a resin portion for sealing the semiconductor  
chip, and  
the first radio communication element is provided inside or on a surface of the  
resin portion.

Application Serial No: 10/564,114

Responsive to the final Office Action mailed on: May 22, 2009

4. (Currently Amended) The module according to claim 1, wherein ~~each of the plurality of semiconductor packages further comprises a shielding layer~~ is provided for blocking an electromagnetic wave.

Claims 5-7. (Cancelled)

8. (Original) The module according to claim 1, wherein the substrate is a single-sided substrate obtained by forming a conductor pattern on only one principal surface of a base or a double-sided substrate obtained by forming a conductor pattern on both principal surfaces of the base, and

each of the plurality of semiconductor packages is mounted on the conductor pattern.

9. (Original) The module according to claim 8, wherein the conductor pattern is constituted by at least one terminal selected from the group consisting of a power source terminal and a ground terminal.

Claims 10-11. (Cancelled)